APPLICATION FOR EXTENSION OF ESCC TECHNOLOGY FLOW APPROVAL

Component Title:

Thin Film Technology for Chip, Wraparound, Single and Network Resistors, Fixed

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Executive

CNES

Date: 23/01/2015

287D

		nember:	100	41-71-7		
Technology Flow submitted for	or Extension	of Qualification App	proval:		L	
SUMMARY DESCRIPTION		TES	ST STRUCTURES	COMPONENTS PROPOSE	D FOR QUALIFICATION	
P: Single resistor 0402, 0 0805, 1206, 2010 chip PRA: 2 to 8 resistors of s value, based on 0603 (PR 0805 (PRA135) or 1206 (I units CNW: 2 to 8 resistors with two different values with the form factor as PRA Substrate: Alumina Resistive layer: Nickel Ch Protection: Silicium nitrida Termination: Nickel Barrie Processes: Thin Film dep Finish: SnPbAg or Au	imilar RA 100), PRA182) h at least he same promium e er	P0402, P0603, with min., critic values, PRA100, PRA1	P0805, P1206 and P2010 all resistance and max. 35, PRA182 with min., see and max. values.	By form factor: ESCC4001023 var. 15 and 13, 14(*) ESCC4001023 var. 01, 05 (*) and 09 ESCC4001023 var. 02, 06 (*) and 10 ESCC4001023 var. 03, 07 (*) and 11 ESCC4001023 var. 04, 08 (*) and 12 ESCC4001025 var. 01 to 07, 22 to 28 ESCC4001025 var. 08 to 14, 29 to 35 ESCC4001025 var. 15 to 21, 36 to 42 (*) Note that gold finish variants are not intended for de-golding and tinning		
Component Manufacture	r 2	Location of M	lanufacturing Plant(s) 3	Date of original qualification a	pproval: 4	
VISHAY SA		Nice (France)	CONTRACTOR	Date: 15/02/2009		
Division Résistances de Haute Précision	Très	Nice (France)		Certificate Ref No. 287		
ESCC Specifications used for Maintenance testing:	5	Deviations to LVT Specification used	testing and Detail 6	Qualification Extension Repor reference and date:	t 7	
Generic: 4001 Issu	ie: 4	No □ Yes		QML Quality Synthesis reports : QML 2013 Synthesis, including PHR0402 Qualification report,		
Detail(s): 4001/023 Issu	ie: 11	Deviation from	Box 15) current Specifications:			
Made processor and the	e: 7	No ⊠ Yes	☐ (Supply details)	QML 2014 Synthesis, 20)/12/2014	
Summary of procurement or e	quivalent tes	t results during curr	ent validity period in support of th	I is application (those to ESCC lis	ited first) 8	
Note that 2013 data are avai	lable from th	ne 2013 QML Synth	esis Report, 2014 summary is	available in Annex 2 box 22.		
1.44.4	1000					
				tolayir		
		2.				
	(4:m)				100 Failina (100 F	
PID changes since start of qua	alification	9	Current PID Verified by:	CNES	10	
None			See the new teams.	Name of Excutive Represe	entative	
Minor* ⊠ Major* □ *Provide details in box:			Ref No: PID-TFD P PR			
19	details in box	C	Rev. 0 22/01/2015	Date:	02/02/2015	
Current Manufacturing facilitie	s surveyed b	y: ESA and		on 22/01	/2015 11	
		MARIN	Executive Representative)	•	Date)	
Satisfactory: Yes	\boxtimes	No 🗆	Explain		5 52	
	0 007//	V00/0045				
Report Reference: CNE	S - DCT/AC	/CQ/2015-01664	-			



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Failure Analysis, DPA, NCCS available:

(Supply data)

8D reports 114006, 114012, 114018, 114020,

114032, 114037

Ref. No's and purposes:

Post or pre-assembly peeling of top metallization: 114006 (PRAHR dc1246), 114018 (P1206 dc 1234), 114032 (PFRR1206 dc 1421), 114037 (PFRR0603 dc 1304)

The undersigned hereby certifies on behalf of the ESCC Executive - that the above information is correct; that the appropriate documentation has been evaluated; - that full compliance to all ESCC requirements is evidence (except as stated in box 15;) - that the reports and data are available at the ESCC Executive and therefore applies on behalf of CNES as the responsible Executive Member for ESCC qualification status to be extended to the component(s) listed herein. 13

Date:

03/02/2015

JP. BUSSENOT

(Signature of the Executive Coordinator)

Continuation of Boxes above:

Box 6: Periodic Testing is defined in paragraph 6 of the Technology Flow PID (See page 3)

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	Non com	pliance to	ESCC	requirements:
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No.: Specification Paragraph Non compliance

Chart F4 testing replaced with the implementation of periodic testing as described in box 16

Additional tasks required to achieve full compliance for ESCC qualification or rationale for acceptability of noncompliance:

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None

PRELEVEMENT PHR	PRA/CNW HR (I4 mini)	ESSAIS	SPECIFICATION
3 mois / 10p		Pliage	ESCC 4001 Para 8.11.2.2
3 mois / 10p	6 mois / 5p	VRT (pièces montées pour CMS)	ESCC 4001 Para 8.8
3 mois / 20p		Séquence Climatique	ESCC 4001 Para 8.10
Note 1	12 mois / 10p	Endurance 2000h	ESCC 4001 Para 8.13
3 mois / 10p	6 mois / 5p	Soudure : 1) Soudabilité 2) Résistance chaleur de soudage	ESCC 4001 Para 8.14 & 8.12
3 mois / 10p	6 mois / 10p	CT (+ Tracking sur PRA/CNW)	ESCC 4001 Para 8.3.3

Note 1 : See PID, includes PFRR ESCC 26000 testing for Ohmic value > 99.9 ohm and yearly 2 000 hours for values < 100 ohms

Executive Manager Disposition	17

Application Approval: Yes □ No □
Action / Remarks:

Date:

Signature, ESA Representative



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ANNEX 1: LIST OF TESTS DONE TO SUPPORT EXTENSION OF QUALIFICATION

Tests conducted in compliance with:

ESCC 4001 generic specification; Chart F4 (for ESCC/QPL parts); or PID-TFD P PRA CNW Issue 7 (for ESCC/QML parts)

Tests vehicle identification/description:

PHR0402 (x3) dc 1338 (Chart F4), 1438 PHR0603 dc 1302, 1308, 1347, (x2) 1413 (LVT3) PHR2010 dc 1319, 1343, 1416, 1439 1438 PRAHR dc 1321, 1342, 1347, 1413 CNWHR dc 1312, 1320, 1337, 1410 PHR0805 dc 1344, 1350, 1406 PHR1206 dc 1308, 1331, 1345, 1414 (LVT1)

Detail Specification reference:

4001/023 & /025

Chart F4	Test	Tick when done	Conditions	Date Code	Tested Qty	N° of Rejects	Comments if not performed, Comments on Rejection
	Mounting	Ø	IEC 60115-1 clause 4.31	1344 1345 1342 1347 1337 1406 1350 1343 1319 1413		o	
	Rapid Change Of Temperature	Ø	IEC 60068-2-14	1344 1345 1342 1347 1337 1406 1350 1343 1319 1413		o	
	Vibration		IEC 60068-2-6				NA
dno	Climatic test Sequence	8	ESCC 4001, Para 8.10	1344 1345 1406 1350 1343 1319	10 10 10 10 10	0	
nggn	Seal Test		IEC 60068-2-17				NA
Environmental Mechanical Subgroup	Mounting	⊠	IEC 60115-1 clause 4.31	1347 1344 1345 1406 1350 1343 1319 1416	55555555	0	
	Robustness of Terminations	Ø	IEC 60068-2-21	1347 1344 1345 1406 1350 1343 1319 1416	5 5 5 5 5 5 5 5 5 5 5 5 5 5 5 5 5 5 5	0	
	Climatic test Sequence		ESCC 4001, Para 8.10				NA vs PID
	Seal Test		IEC 60068-2-17				NA .
	Resistance to Soldering Heat	Ø	IEC 60068-2-20	1347 1344 1342 1347 1337 1406 1350 1319 1416 1413	55333555555	0	
	Mounting		IEC 60115-1 clause 4.31				
18	Climatic test Sequence		ESCC 4001, Para 8.10				NA vs PID
	Seal Test		IEC 60068-2-17				NA
	Mounting		IEC 60115-1 clause 4,31				

	Insulation Resistance		ESCC 4001, Para 8.3.1.2				NA vs PID
	Voltage Proof		ESCC 4001, Para 8.3.1.3			SHOT.	NA vs PID
group	Mounting	⊠	IEC 60115-1 clause 4.31	1342 1347 1337	5 5 5	0	PRA / CNW
Endurance Subgroup	Operating Life	Ø	ESCC 4001, Para 8.13	1342 1347 1337 1413 1410	5 5 5 5 5	0	PRA / CNW
E	Seal Test		IEC 60068-2-17				NA
Assembly Capability Subgroup	Solderability	Ø	IEC 60068-2-20	1347 1344 1342 1347 1337 1406 1350 1343 1319 1413	555555555555	0	
Assemb	Permanence of marking	Ø	ESCC 24800	1342 1347 1337 1413 1410	2 2 2 2 2	0	PRA / CNW
Failure Rate Endurance Subgroup	Operating Life	⊠	ESCC 4001, Para 8.13	Various	120 400 400	0	2 000H 4 000H 8 000H
	Seal Test		IEC 60068-2-17				NA
Additional Tests	High & Low Temp (Temperature Coefficient)	Ø	ESCC 4001	1347 1344 1345 1342 1347 1397 1406 1350 1343 1319 1416 1413	5485555543355	0	
		0					



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	NOTES ON THE COMPLETION OF THE APPLICATION FORM FOR ESCC QUALIFICATION EXTENSION APPROVAL
ENTRIES	
Form heading	shall indicate: - the title of the component as given in its detail specification or the name of the series, family; - the Executive Member; - the entering date; - the certificate number and its sequential suffix.
Box 1	shall provide details given in the table; in particular there shall be listed: - the variants or range of variants; - the range of components (the ESCC code is recommended to indicate the values or values range, the tolerance, the voltage, etc); the designation given in the detail specification as 'base on'; - under Test Vehicle enter either an ESCC code or the specific characteristic capable of identifying the component tested (e.g., voltage of coil for a relay); - under component similar enter a cross if relevant.
Box 2; 3 and 4	As per QPL entry; otherwise, an explanation of the changes must be supplied.
Box 5	Will show the ESCC Generic and Detail specifications, including issue number and revision letter, current at the time the tests reported were performed. If the specifications are different from those current on the date of the application, see Box 6.
Box 6	Will show the deviations from the Generic and Detail Specifications listed in Box 5, in particular deviations from testing. In case of deviations this must be listed in Box 15. In case the referenced specification in Box 5 have currently a different issue and/or revision indicate also whether the test data deviates or not from such current documents.
Box 7	Must reference the report(s) supplied in support of the application.
Box 8	Should provide the details of procurement to the full ESCC System, documentation of all of which should already have been delivered to the ESCC Executive under the terms of the relevant Generic Specification. An appropriate table has been drawn in this box.
Box 9	If the PID evolved after the Original Qualification or after the last Extension of Qualification, adequate details of such evolution shall be provided together with the reasons for the changes. Major changes shall be clearly marked.
Box 10	Identify the current PID issue status, date and actual date of verification. The date of verification of the current PID should be arranged as close as possible to the required date of extension.
Box 11	This box can be completed only after a physical visit to the plant to confirm that no unexplained changes occurred and that the practices, procedures, material, etc. used in manufacturing the components are as described in the PID. This survey shall be carried out in accordance with the requirements of ESCC Basic Specification No. 20200 and its findings shall be recorded.
Box 12	Provide details of, or reference to, any Destructive Physical Analysis (DPA) and Failure Analysis reports as well as any Nonconformance(s) (NCCS) occurred during the qualification validity period, stating if established corrective action have produced satisfactory results.
Box 13	Enter only the name of the Executive Member (i.e., CNES, DLR, ESTEC, etc.) and the signature of the responsible Executive Coordinator.
Box 14	To be used when there is a need to expand any of the boxes from 1 through 12. Identify box affected and reference the Box 14 in the relevant Box. Box 14 can be broken into 14a, 14b, etc. if several boxes have to be expanded.
Box 15	Fill in Table as requested.
Box 16	Any additional action deemed necessary by the Executive Member to bring the submitted data to a standard likely to be accepted by the ESCC Executive should be listed herein or the reason(s) to accept the noncompliance.
Box 17	All Executive Manager recommendations on the application itself, special conditions or restrictions, modifications of the QPL or QML entry, letters to the manufacturer, etc. shall be entered clearly in Box 19, signed by the representative for ESA, and dated.
Box 18	Fill in Table as requested.

Box 19 Confidential Details of PID changes including those of a confidential nature, shall be provided.

Box 20 State noncompliance with reference to specification(s) and paragraph(s). To simplify reference in Box 16 each nonconformance

shall be sequentially numbered. If relevant state 'None',

Any additional action deemed necessary by the Executive Member to bring the submitted data to a standard likely to be accepted by the ESCC Executive should be listed herein or the reason(s) to accept the noncompliance. Box 21

Box 22 Additional Comments.